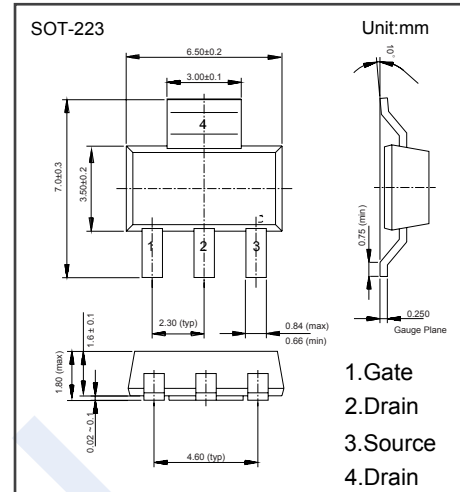
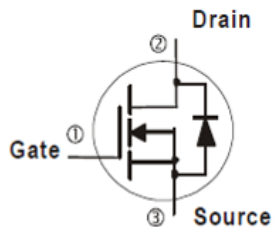


## N-Channel MOSFET

### NFT1N60

#### ■ Features

- $V_{DS} (V) = 600V$
- $I_D = 0.4 A (V_{GS} = 10V)$
- $R_{DS(ON)} < 7.9 \Omega (V_{GS} = 10V)$
- High switching speed
- Improved dv/dt capability



#### ■ Absolute Maximum Ratings $T_a = 25^\circ C$

Parameter	Symbol	Rating	Unit	
Drain-Source Voltage	$V_{DS}$	600	V	
Gate-Source Voltage	$V_{GS}$	$\pm 30$		
Continuous Drain Current	$I_D$	0.4	A	
Pulsed Drain Current	$I_{DM}$	1.6		
Single Pulse Avalanche Energy	$E_{AS}$	52	mJ	
Power Dissipation	$P_D$	$T_c = 25^\circ C$	3.3	W
		Derate above $25^\circ C$	0.026	W/ $^\circ C$
Thermal Resistance.Junction- to-Ambient	$R_{\theta JA}$	37.9	$^\circ C/W$	
Junction Temperature	$T_J$	150	$^\circ C$	
Storage Temperature Range	$T_{stg}$	-55 to 150		

## N-Channel MOSFET

### NFT1N60

#### ■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V <sub>DSS</sub>	I <sub>D</sub> =250 μA, V <sub>GS</sub> =0V	600			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =600V, V <sub>GS</sub> =0V			1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±30V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250 μA	2		4	V
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =0.5A			7.9	Ω
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =25V, f=1MHz		148		pF
Output Capacitance	C <sub>oss</sub>			28		
Reverse Transfer Capacitance	C <sub>rss</sub>			0.3		
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =480V, I <sub>D</sub> =1A		3.1		nC
Gate Source Charge	Q <sub>gs</sub>			1.3		
Gate Drain Charge	Q <sub>gd</sub>			0.4		
Turn-On DelayTime	t <sub>d(on)</sub>	V <sub>DS</sub> =300V, I <sub>D</sub> =1A, R <sub>GEN</sub> =25 Ω		6		ns
Turn-On Rise Time	t <sub>r</sub>			20		
Turn-Off DelayTime	t <sub>d(off)</sub>			9		
Turn-Off Fall Time	t <sub>f</sub>			26		
Body Diode Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 1A, di/dt= 100A/μs, V <sub>GS</sub> =0		190		μC
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			0.53		
Maximum Continuous Drain-Source Diode Forward Current	I <sub>S</sub>				1	A
Maximum Pulsed Drain-Source Diode Forward Current	I <sub>SM</sub>				4	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =1A, V <sub>GS</sub> =0V			1.4	V

Note.: Pulse width ≤ 300μs, Duty cycle ≤ 2%

#### ■ Marking

Marking	1N60
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## N-Channel MOSFET NFT1N60

■ Typical Characteristics

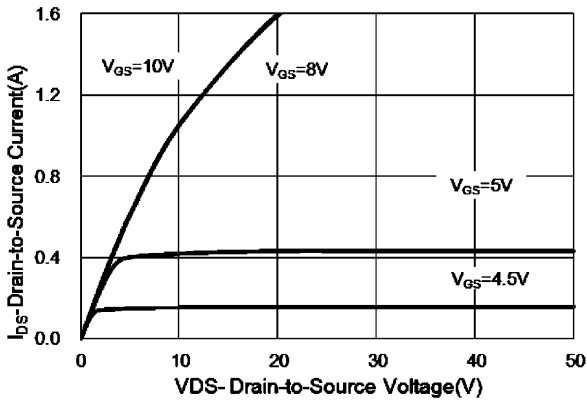


Fig.1 Output Characteristics

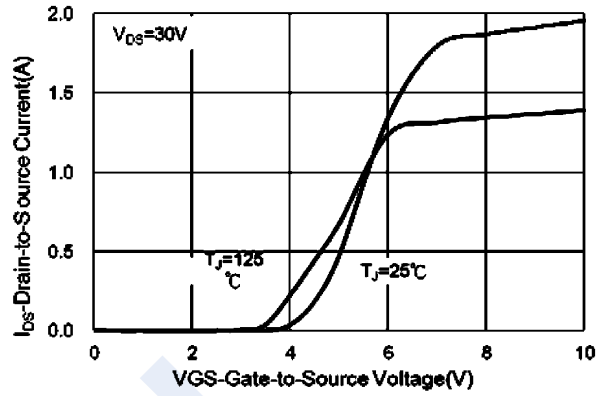


Fig.2 Transfer Characteristics

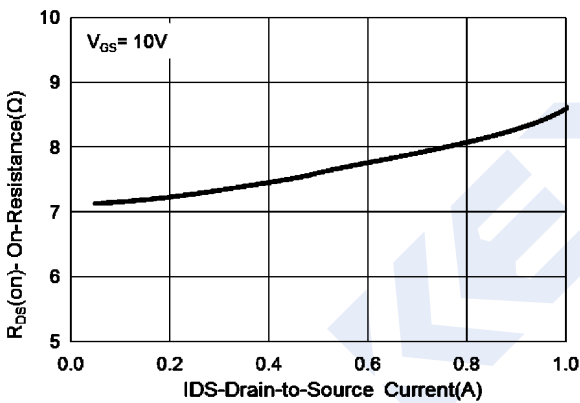


Fig.3 On-Resistance vs. Drain Current

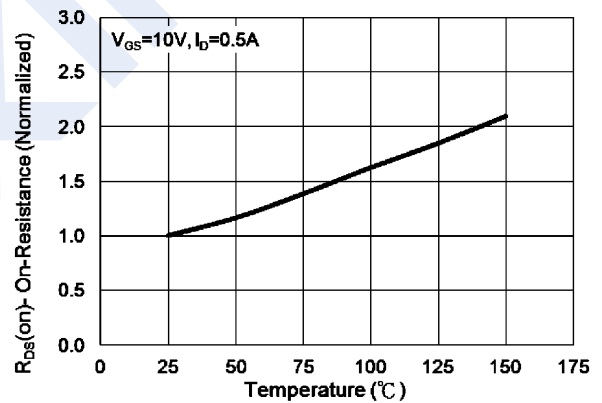


Fig.4 On-Resistance vs. Junction Temperature

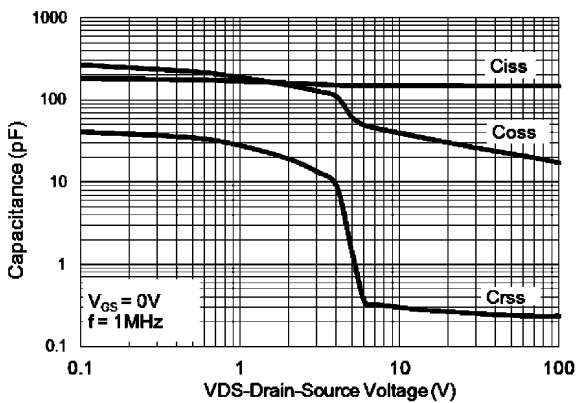


Fig.5 Capacitance vs. Drain-Source Voltage

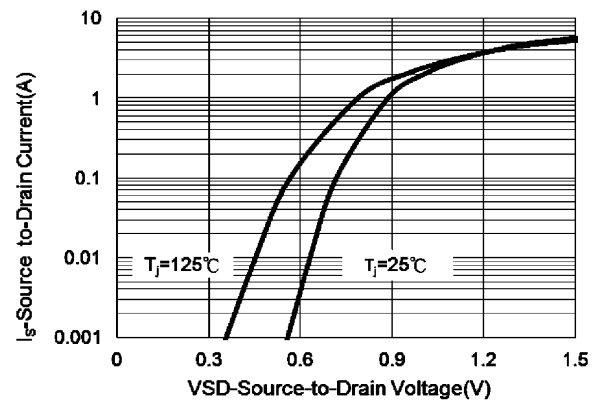


Fig.6 Source-Drain Diode Forward Voltage

## N-Channel MOSFET NFT1N60

■ Typical Characteristics

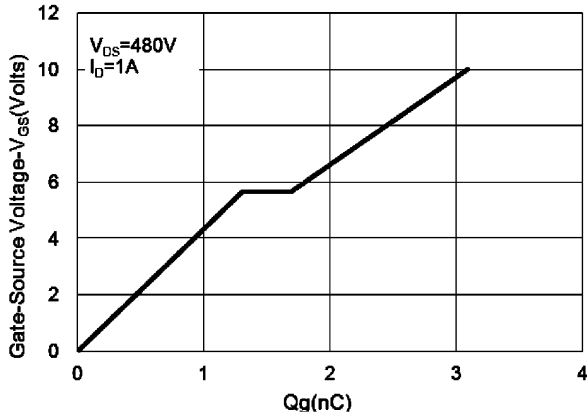


Fig.7 Gate Charge

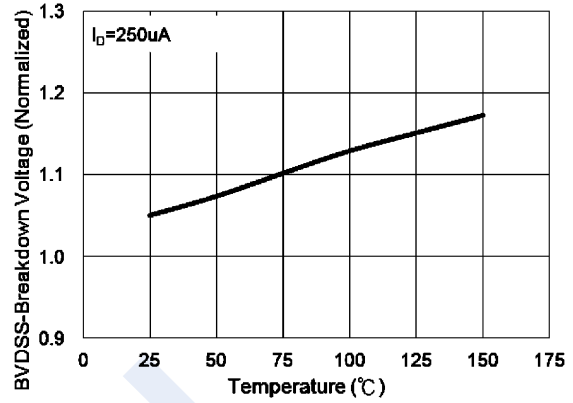


Fig.8  $BV_{DSS}$  vs. Junction Temperature

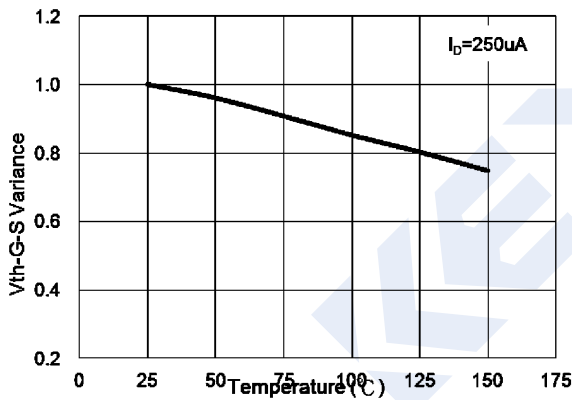


Fig.9 Threshold Voltage Variation with Temperature

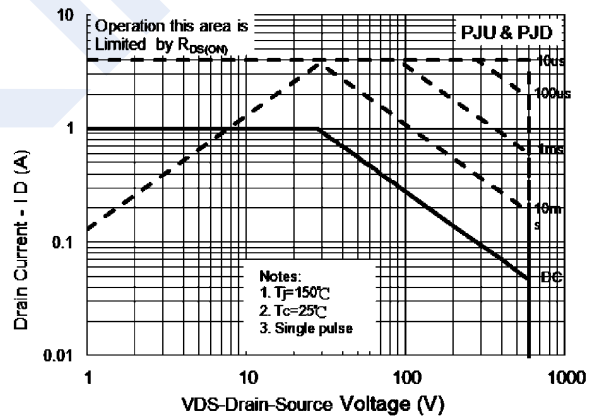


Fig.10 Maximum Safe Operating Area

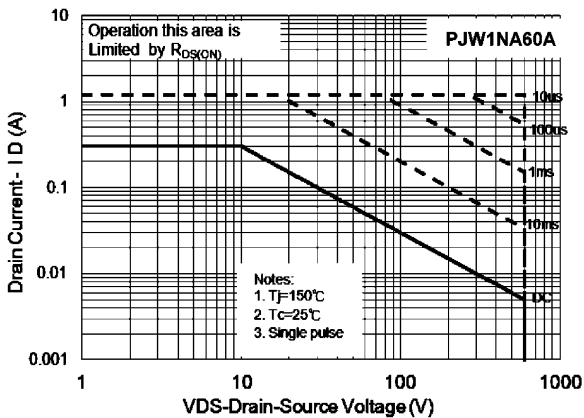


Fig.11 Maximum Safe Operating Area

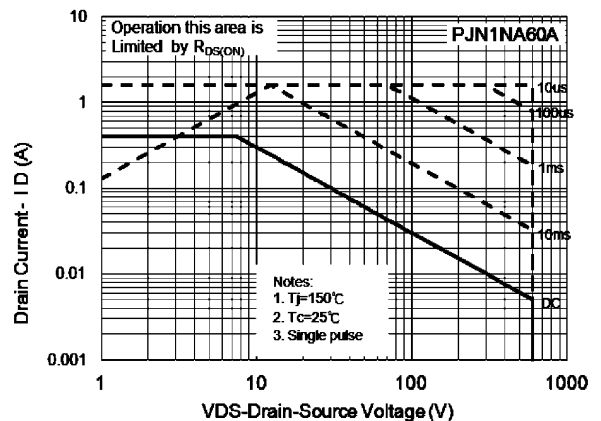


Fig.12 Maximum Safe Operating Area

## N-Channel MOSFET NFT1N60

■ Typical Characteristics

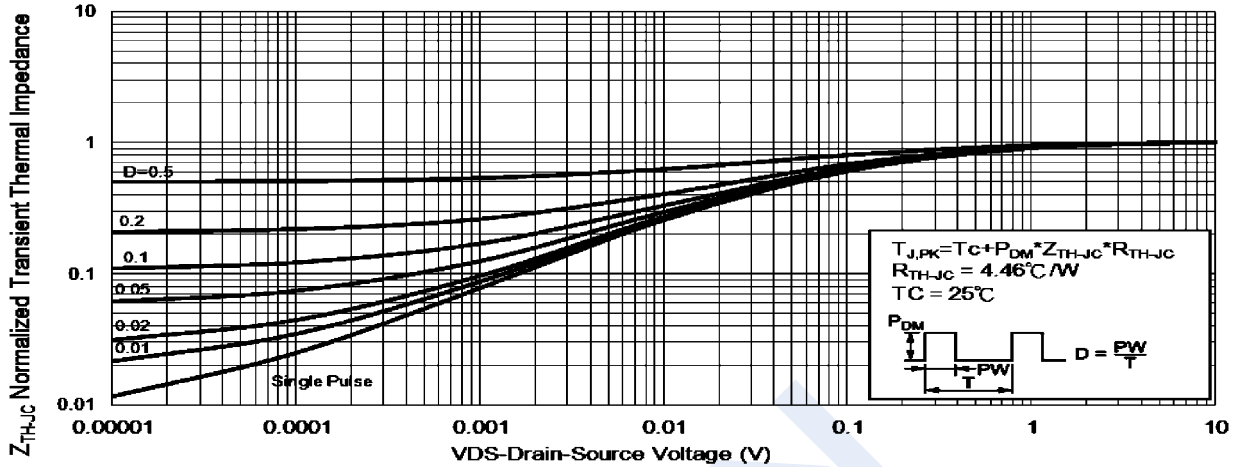


Fig.12 PJU/PJD Normalized Transient Thermal Impedance vs. Pulse Width

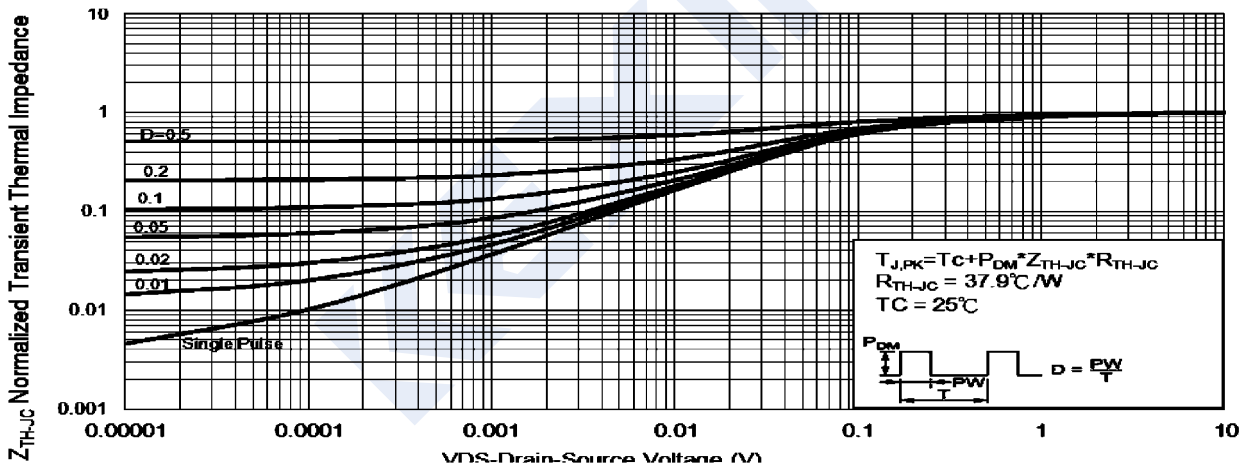


Fig.13 PJW1NA60A Normalized Transient Thermal Impedance vs. Pulse Width

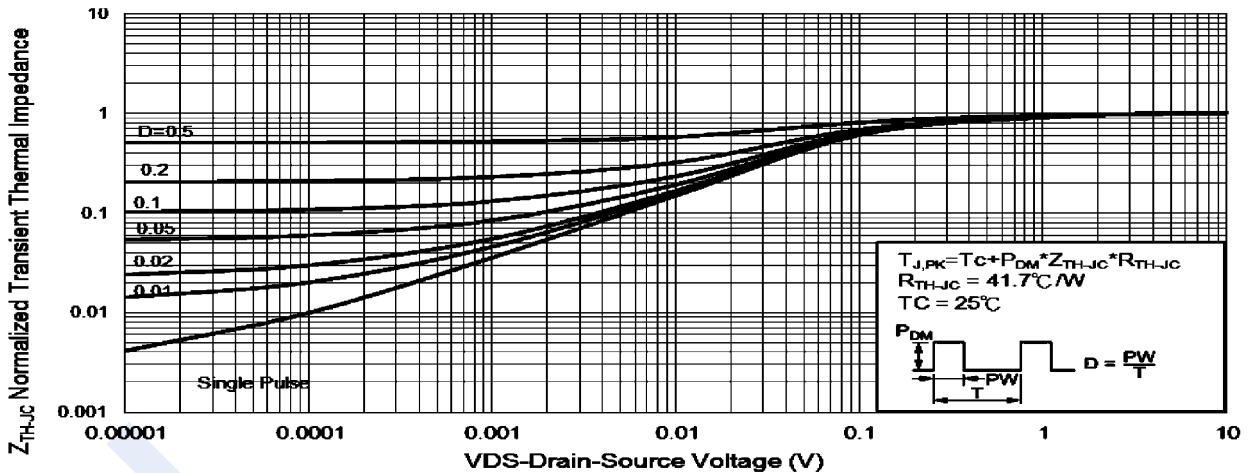


Fig.15 PJN1NA60 Normalized Transient Thermal Impedance vs. Pulse Width